

N-CHANNEL ENHANCEMENT MODE MOSFET

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Features

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive

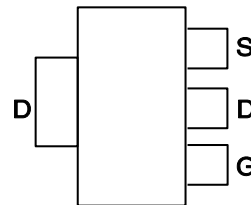
Applications

- DC-DC Converters
- Audio Output Stages
- Relay and Solenoid Driving
- Motor Control

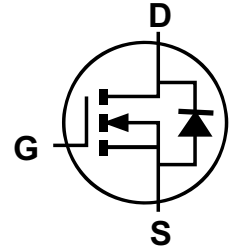
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208

SOT223



Pin Out - Top View



Equivalent Circuit



Top View

Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D $T_A = +25^\circ\text{C}$
40V	0.05Ω @ $V_{GS} = 10\text{V}$	7A

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	40	V
Gate-Source Voltage			V_{GS}	±20	V
Continuous Drain Current	$V_{GS} = 10\text{V}$	$T_A = +70^\circ\text{C}$ (Note 2)	I_D	7	A
		(Note 1)		5.6	
				5	
Pulsed Drain Current	$V_{GS} = 10\text{V}$	(Note 3)	I_{DM}	22	A
Continuous Source Current (Body Diode)			I_S	5.4	A
Pulsed Source Current (Body Diode)			I_{SM}	22	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 1)	P_D	2	W mW/°C
	(Note 2)		16	
			3.9	
Thermal Resistance, Junction to Ambient	(Note 3)	$R_{\theta JA}$	31	°C/W
	(Note 2)		62.5	
			32.2	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

- Notes:
1. For a device surface mounted on 25mm x 25mm FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 2. For a device surface mounted on FR-4 PCB measured at $t \leq 5$ seconds.
 3. Repetitive rating 25mm x 25mm FR-4 PCB, D = 0.05, pulse width 10μs - pulse width limited by maximum junction temperature.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	40	–	–	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	–	–	1	μA	V _{DS} = 40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	–	–	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	1	–	2	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 8)	R _{DS(ON)}	–	–	0.05	Ω	V _{GS} = 10V, I _D = 4.5A
				0.075		V _{GS} = 4.5V, I _D = 3.2A
Forward Transconductance	g _{fs}	–	8.7	–	S	V _{DS} = 15V, I _D = 2.5A
Diode Forward Voltage (Note 8)	V _{SD}	–	0.8	0.95	V	I _S = 2.5A, V _{GS} = 0V, T _J = +25°C
Reverse Recovery Time (Note 9)	t _{RR}	–	19.86	–	ns	I _F = 2.5A, di/dt = 100A/μs, T _J = +25°C
Reverse Recovery Charge (Note 9)	Q _{RR}	–	16.36	–	nC	
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	–	770	–	pF	V _{DS} = 40V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	–	92	–	pF	
Reverse Transfer Capacitance	C _{rss}	–	61	–	pF	
Total Gate Charge	Q _g	–	18.2	–	nC	V _{DS} = 30V, V _{GS} = 10V, I _D = 2.5A (Refer to test circuit)
Gate-Source Charge	Q _{gs}	–	2.1	–	nC	
Gate-Drain Charge	Q _{gd}	–	4.5	–	nC	
Turn-On Delay Time	t _{D(ON)}	–	2.55	–	ns	V _{DD} = 30V, V _{GS} = 10V I _D = 2.5A, R _G = 6Ω (Refer to test circuit)
Turn-On Rise Time	t _r	–	4.45	–	ns	
Turn-Off Delay Time	t _{D(OFF)}	–	28.61	–	ns	
Turn-Off Fall Time	t _f	–	7.35	–	ns	

Notes: 8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

RATING AND CHARACTERISTICS CURVES (RM7N40S4)

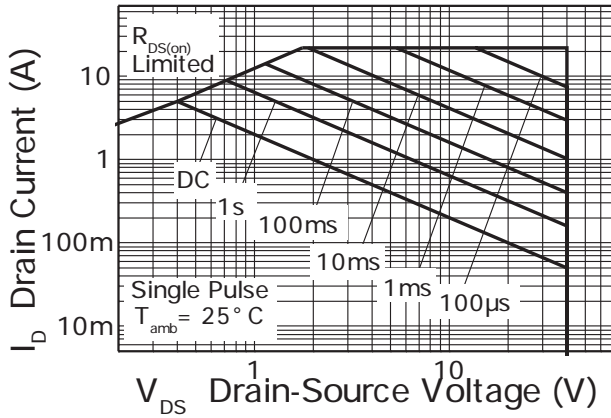


FIG 1, Safe Operating Area

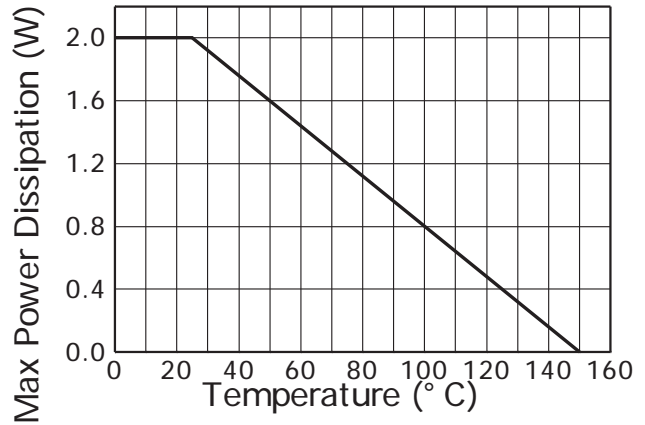


FIG 2, Derating Curve

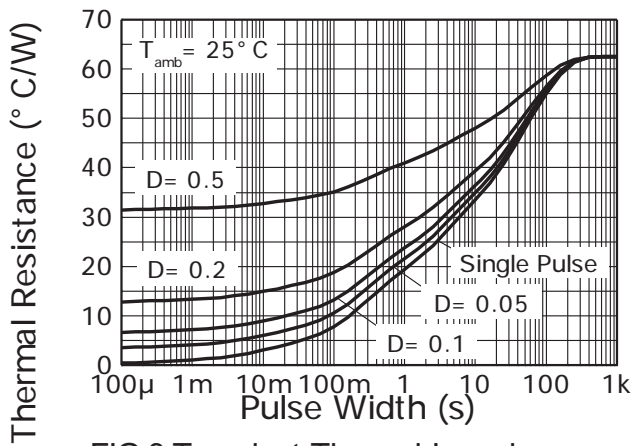


FIG 3, Transient Thermal Impedance

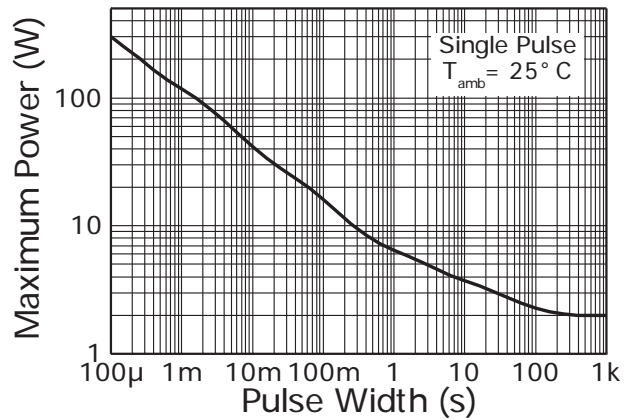


FIG 4, Pulse Power Dissipation

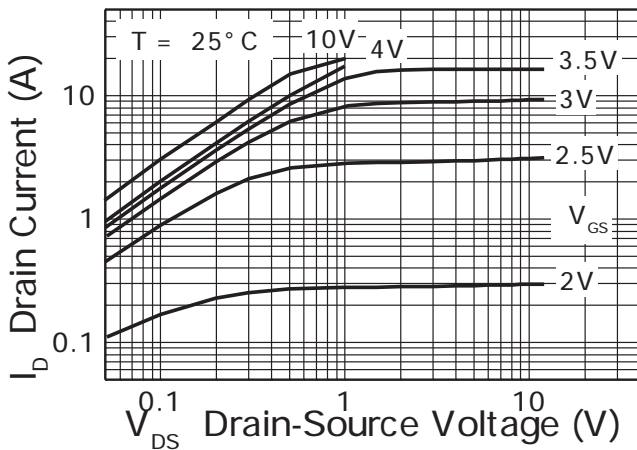


FIG 5, Output Characteristics

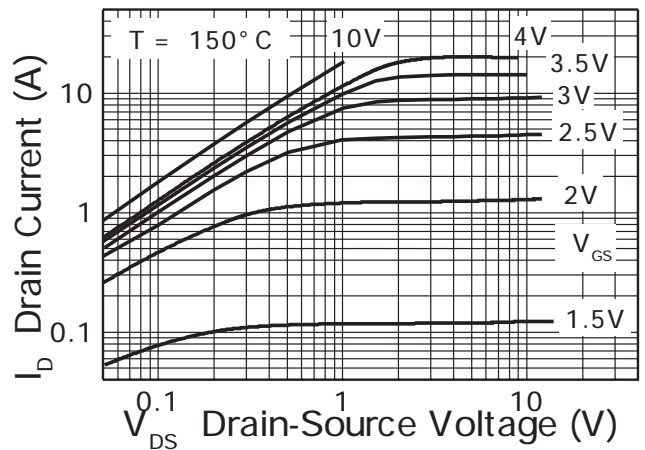


FIG 6, Output Characteristics

RATING AND CHARACTERISTICS CURVES (RM7N40S4)

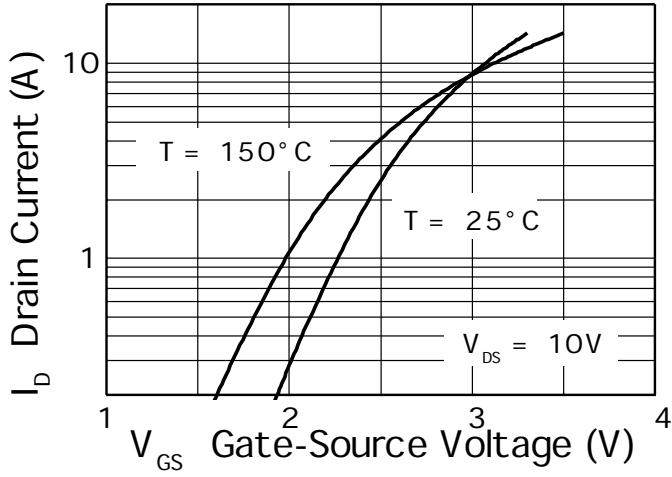


FIG 7, Typical Transfer Characteristics

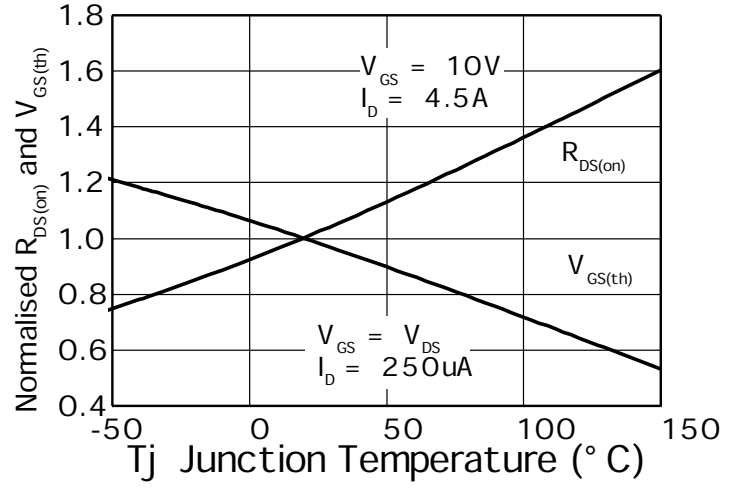


FIG 8, Normalised Curves v Temperature

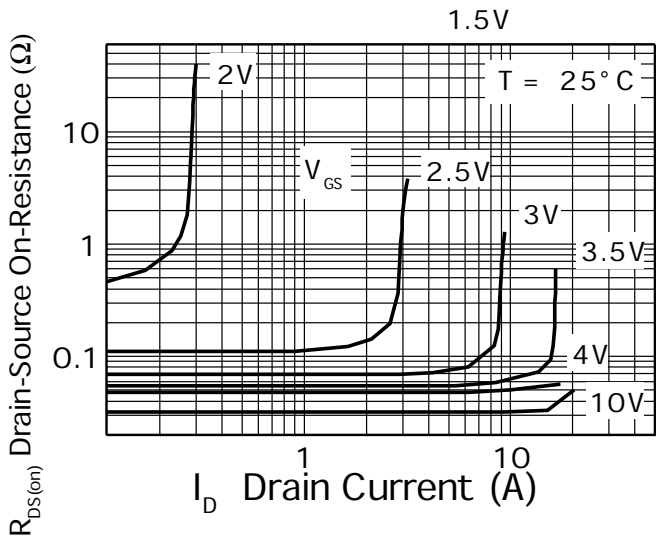


FIG 9, On-Resistance v Drain Current

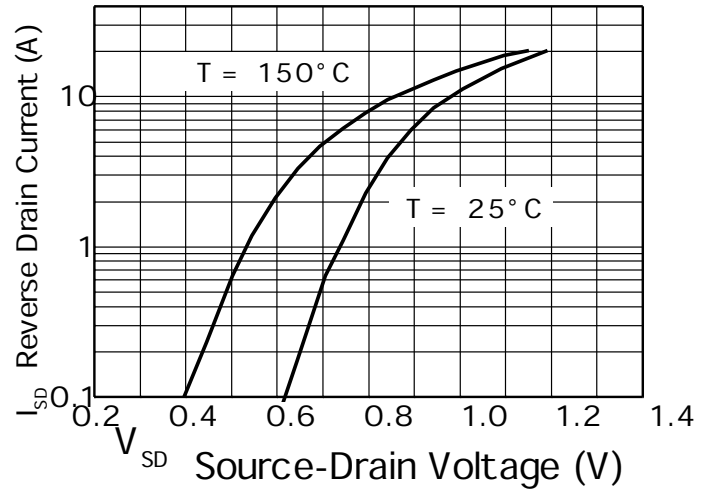
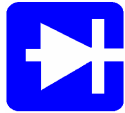
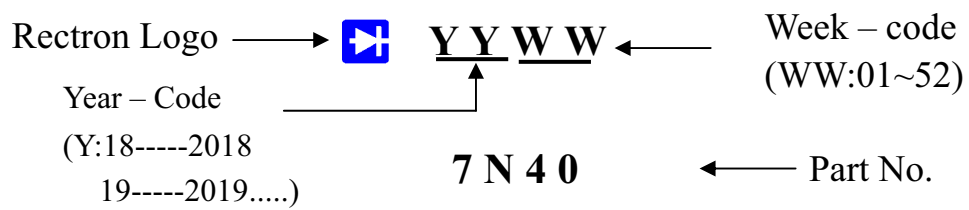


FIG 10, Source-Drain Diode Forward Voltage

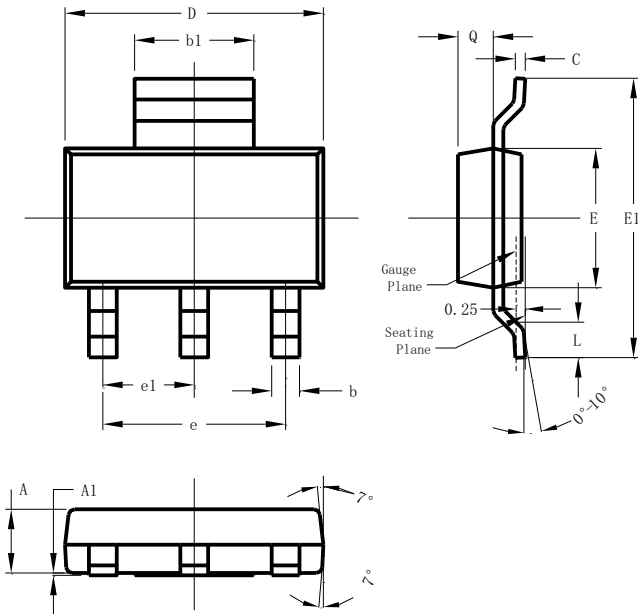


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Marking on the body

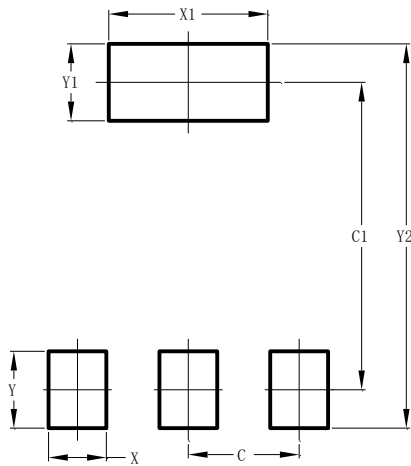


Package Outline Dimensions



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

Package	Tube (pcs/tube)	Tube (pcs/inner box)	Tube (pcs/cartoon)	Tape&Reel (pcs/reel)	Tape&Reel (pcs/inner box)	Tape&Reel (pcs/cartoon)
DFN5x6/DFN3x3	100	10,000	100,000	2,500	5,000	40,000
DFN1006	—	—	—	10,000	10,000	400,000
SOP-8	100	10,000	100,000	4,000	4,000	20,000
TSSOP-8	100	32,000	128,000	3,000	6,000	48,000
SOT-23-3L	—	—	—	3,000	30,000	120,000
SOT-23-6L	—	—	—	3,000	30,000	120,000
SOT-23(6R)	—	—	—	3,000	30,000	120,000
SOT-363	—	—	—	3,000	30,000	120,000
SOT-523	—	—	—	3,000	30,000	120,000
SOT223	—	—	—	2,500	2,500	20,000
TO-220	50	1,000	5,000	—	—	—
TO-220F	50	1,000	10,000	—	—	—
TO-247	30	300	1,200	—	—	—
TO-251	80	4,000	40,000	—	—	—
TO-251S(4R)	80	4,000	40,000	—	—	—
TO-252-2L(4R)	80	4,000	40,000	2,500	2,500	25,000
TO-263-2L	50	1,000	10,000	800	800	8,000
TO-3P	30	300	3,000	—	—	—
TO-92	—	—	—	1,000(袋装)	10,000	100,000

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